

PATENT ASSIGNMENT COVER SHEET


Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5050291

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HYUNMIN JUNG	06/27/2018
SUNWOONG KIM	06/27/2018
HYOKEUN LEE	06/27/2018
WOOJAE SHIN	06/27/2018
HYUK-JAE LEE	06/27/2018
RECEIVING PARTY DATA	
Name:	SK HYNIX INC.
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB
City:	ICHEON-SI GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Name:	SEOUL NATIONAL UNIVERSITY R&DB FOUNDATION
Street Address:	1, GWANAK-RO, GWANAK-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	08826
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16035389
CORRESPONDENCE DATA	
Fax Number:	(630)323-0335
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	uspto.actions@wpapat.com
Correspondent Name:	WILLIAM PARK & ASSOCIATES LTD.
Address Line 1:	930 N. YORK ROAD, SUITE 201
Address Line 4:	HINSDALE, ILLINOIS 60521
ATTORNEY DOCKET NUMBER:	PA3505-0
NAME OF SUBMITTER:	W. WILLIAM PARK
SIGNATURE:	/W. William Park/

DATE SIGNED:	07/13/2018
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 2 source=PA3505-0_DEC_ASSGN#page1.tif source=PA3505-0_DEC_ASSGN#page2.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention	SEMICONDUCTOR DEVICE FOR MANAGING WEAR LEVELING OPERATION OF A NONVOLATILE MEMORY DEVICE	
Declaration	<p>As the below named inventor(s), I hereby declare that:</p> <p>The declaration is directed to:</p> <p><input checked="" type="checkbox"/> The attached application, or</p> <p><input type="checkbox"/> United States application or PCT international application number _____ filed on _____</p> <p>The above-identified application was made or authorized to be made by me.</p> <p>I believe that I am the original or an original joint inventor of a claimed invention in the application.</p> <p>I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.</p>	
Assignment	<p>NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledged, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s)</p> <p>SK Hynix Inc., located at 2091, Gyeongchung-daero, Bubal-eup, Icheon-si, Gyeonggi-do, 17336, Republic of Korea, and Seoul National University R&DB Foundation, located at 1, Gwanak-ro, Gwanak-gu, Seoul, 08826, Republic of Korea</p> <p>and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreign countries any and all improvements thereof, the entire rights, title and interest in and to any and all Patents which may be granted therefore in the United States. I hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in and to the same, for his sole use and for the use of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.</p> <p>I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary.</p> <p>I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.</p> <p>I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will testify as to the same in any litigation related thereto and will promptly execute and deliver to assignee(s) or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.</p>	
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Hyunmin JUNG
	Inventor Signature	
	Date	2019. 6. 27

A total of 1 supplemental sheet(s) are attached hereto for additional inventors, if any.

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Legal Name Of Inventor	Inventor Name (First Middle LAST):	Sunwoong KIM
	Inventor Signature:	<i>Sunwoong Kim</i>
	Date:	2018. 06. 29
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Hyocheon LEE
	Inventor Signature:	<i>Hyocheon Lee</i>
	Date:	2018. June. 29
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Woojae SHIN
	Inventor Signature:	<i>Woojae Shin</i>
	Date:	2018. 6. 29
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Hyuk-Jae LEE
	Inventor Signature:	<i>Hyuk Jae Lee</i>
	Date:	2018. 6. 29